

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of: Wen-Chun Zheng

Attorney Docket:

Serial No.:

Group Art:

Filed:

Examiner:

Title: Elasto-Plastic Sockets for Land or  
Ball Grid Array Packages and  
Subsystem Assembly

Batch No.

INFORMATION DISCLOSURE STATEMENT  
UNDER 37 C.F.R. §§1.97 and 1.98

Commissioner for Patents  
Washington, D.C. 20231

Dear Commissioner:

CERTIFICATE OF EXPRESS MAIL	
"EXPRESS MAIL" mailing label number: <u>ER 032558802 US</u>	
Date of Deposit: <u>2/9/2004</u>	
I hereby certify that the above-identified documents, which are attached, are being deposited with the United States Postal Service "Express Mail Post Office to Addressee" service under 37 C.F.R. ' 1.10 on the date indicated above and is addressed to the Commissioner of Patents and Trademarks, Box Patent Application, Washington, D.C. 20231.	
<u>Wen-chun Zheng</u> Name of Person Mailing Paper or Fee	<u>Wen Zheng</u> Signature

In compliance with the duty of disclosure under 37 C.F.R. §1.56, it is respectfully requested that this Information Disclosure Statement be entered and the reference(s) listed on attached Form PTO-1449 be considered by the Examiner and made of record. In accordance with 37 C.F.R. § 1.98(d), copies of the listed references are enclosed.

In accordance with 37 C.F.R. §§ 1.97(g),(h), this Information Disclosure Statement is not to be construed as a representation that a search has been made, and is not to be construed to be an admission that the information disclosed is, or is considered to be, prior art with respect to the present application or material to patentability as defined in 37 C.F.R. §§ 1.56.

The present Information Disclosure statement is being filed prior to the receipt of a first Official Action reflecting an examination on the merits and hence is believed to be timely in accordance with 37 C.F.R. § 1.97(b).

2/9/2004  
Date

Respectfully submitted,  
Wen-Chun Zheng  
Wen-Chun Zheng